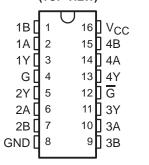
SLLS144E - OCTOBER 1980 - REVISED APRIL 2000

- Meet or Exceed the Requirements of TIA/EIA-422-B, TIA/EIA-423-B, and TIA/EIA-485-A and ITU Recommendations V.10, V.11, X.26, and X.27
- Designed for Multipoint Bus Transmission on Long Bus Lines in Noisy Environments
- 3-State Outputs
- Common-Mode Input Voltage Range of –12 V to 12 V
- Input Sensitivity . . . ±200 mV
- Input Hysteresis . . . 50 mV Typ
- High Input Impedance . . . 12 kΩ Min
- Operate From Single 5-V Supply
- Low Power Requirements
- Pin-to-Pin Replacement for AM26LS32

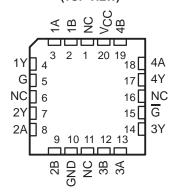
description

The SN55173, SN65173, and SN75173 are monolithic quadruple differential line receivers with 3-state outputs. They are designed to meet requirements of TIA/EIA-422-B, TIA/EIA-423-B, TIA/EIA-485-A, and several ITU recommendations. The standards are for balanced multipoint bus transmission at rates up to 10 megabits per second. The four receivers share two OR enable inputs, one active when high, the other active when low. These devices feature high input impedance, input hysteresis for increased noise immunity, and input sensitivity of ±200 mV over a common-mode input voltage range of –12 V to 12 V. Fail-safe design specifies that if the inputs are open circuited, the outputs are always high. The SN65173 and SN75173 are designed for optimum performance when used with the SN75172 or SN75174 quad differential line drivers.

SN55173 . . . J PACKAGE SN65173, SN75173 . . . D OR N PACKAGE (TOP VIEW)



SN55173 . . . FK PACKAGE (TOP VIEW)



NC-No internal connection

THE SN55173 IS NOT RECOMMENDED FOR NEW DESIGNS.

The SN55173 is characterized over the full military temperature range of −55°C to 125°C. The SN65173 is characterized for operation from −40°C to 85°C. The SN75173 is characterized for operation from 0°C to 70°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



AVAILABLE OPTIONS

	PACKAGED DEVICES									
TA	PLASTIC SMALL OUTLINE (D)	PLASTIC CHIP CARRIER (FK)	CERAMIC DIP (J)	PLASTIC DIP (N)						
0°C to 70°C	SN75173D	_		SN75173N						
-40°C to 85°C	SN65173D	_		SN65173N						
-55°C to 125°C	_	SN55173FK	SN55173J	_						

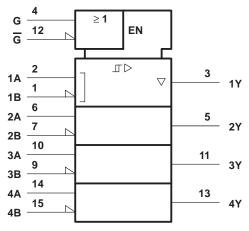
The D package is available taped and reeled. Add the suffix R to the device type (e.g., SN75173DR).

FUNCTION TABLE (each receiver)

DIFFERENTIAL	ENA	BLES	OUTPUT
A–B	G	G	Υ
V > 0.2 V	Н	Х	Н
V _{ID} ≥ 0.2 V	Х	L	Н
0.2 \/ 4 \/ 15 4 0.2 \/	Н	Х	?
$-0.2 \text{ V} < \text{V}_{1D} < 0.2 \text{ V}$	Х	L	?
V-> < 0.2 V	Н	Х	L
V _{ID} ≤ -0.2 V	Х	L	L
X	L	Н	Z
Open circuit	Х	L	Н
Open circuit	Н	Χ	Н

H = high level, L = low level, ? = indeterminate, X = irrelevant, Z = high impedance (off)

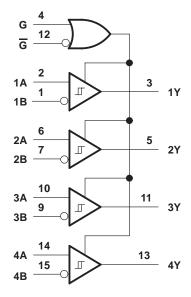
logic symbol †



 \dagger This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the D, J, and N packages.

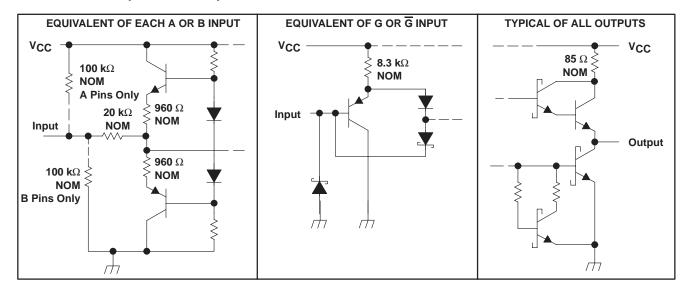


logic diagram (positive logic)



Pin numbers shown are for the D, J, and N packages.

schematics of inputs and outputs



SN55173, SN65173, SN75173 QUADRUPLE DIFFERENTIAL LINE RECEIVERS

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)† Input voltage (V_I or B inputs)±25 V Differential input voltage, V_{ID} (see Note 2)±25 V Low-level output current, IOL 50 mA

Storage temperature range, T_{stq}-65°C to 150°C

- NOTES: 1. All voltage values, except differential input voltage, are with respect to network ground terminal.
 - 2. Differential input voltage is measured at the noninverting input with respect to the corresponding inverting input.
 - 3. The package thermal impedance is calculated in accordance with JESD 51.

DISSIPATION RATING TABLE

PACKAGE	$T_{\mbox{\scriptsize A}} \le 25^{\circ}\mbox{\scriptsize C}$ POWER RATING	DERATING FACTOR	T _A = 70°C POWER RATING	T _A = 125°C POWER RATING
FK	1375 mW	11 mW/°C	880 mW	275 mW
J	1375 mW	11 mW/°C	880 mW	275 mW

recommended operating conditions

		MIN	NOM	MAX	UNIT
Cumply voltage Van	SN55173	4.5	5	5.5	V
Supply voltage, V _{CC}	SN65173, SN75173	4.75	5	5.25	V
Common-mode input voltage, V _{IC}				±12	V
Differential input voltage, V _{ID}				±12	V
High-level enable-input voltage, VIH		2			V
Low-level enable-input voltage, V _{IL}				0.8	V
High-level output current, IOH				-400	μΑ
Low-level output current, IOL				16	mA
	SN55173	-55		125	
Operating free-air temperature, TA	SN65173	-40		85	°C
	SN75173	0		70	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

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electrical characteristics over recommended ranges of common-mode input voltage, supply voltage, and operating free-air temperature

	PARAMETER	TES	T CONDITIONS		MIN	TYP [†]	MAX	UNIT
V _{IT+}	Positive-going input threshold voltage	$V_0 = 2.7 V$,	$I_{O} = -0.4 \text{ mA}$				0.2	V
V _{IT} _	Negative-going input threshold voltage	$V_0 = 0.5 V$,	I _O = 16 mA		-0.2‡			V
V _{hys}	Hysteresis (V _{IT+} – V _{IT} –)	See Figure 4				50		mV
VIK	Enable-input clamp voltage	I _I = -18 mA					-1.5	V
				SN55173	2.5			V
VOH	High-level output voltage	V _{ID} = 200 mV,	I _{OH} = -400 μA	SN65173, SN75173	2.7			V
V	Low level output voltage	V _{ID} = −200 mV,	Soo Figure 1	$I_{OL} = 8 \text{ mA}$			0.45	V
VOL	Low-level output voltage	VID = -200 mv,	See Figure 1	I _{OL} = 16 mA			0.5	
loz	High-impedance-state output current	$V_0 = 0.4 \text{ V to } 2.4 \text{ V}$					±20	μΑ
1.	Line input current	Other input at 0 V,	See Note 3	V _I = 12 V			1	mA
'	Line input current	Other input at 0 v,	See Note 3	$V_{\parallel} = -7 \text{ V}$			-0.8	IIIA
lн	High-level enable-input current	V _{IH} = 2.7 V					20	μΑ
I _{IL}	Low-level enable-input current	V _{IL} = 0.4 V					-100	μΑ
rį	Input resistance				12			kΩ
los	Short-circuit output current				-15		-85	mA
Icc	Supply current	Outputs disabled					70	mA

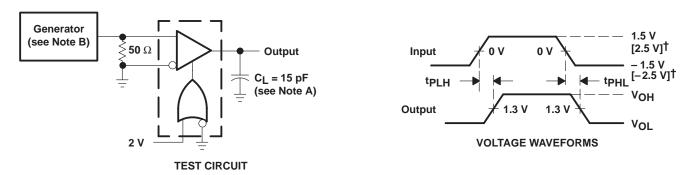
NOTE 3: Refer to TIA/EIA-422-B and TIA/EIA-423-B for exact conditions.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$

	PARAMETER	TEST CO	MIN	TYP	MAX	UNIT	
tPLH	Propagation delay time, low-to-high-level output	$V_{ID} = -1.5 \text{ V to } 1.5 \text{ V},$			20	35	ns
tPHL	Propagation delay time, high-to-low-level output	$C_L = 15 pF$,	See Figure 1		22	35	ns
tPZH	Output enable time to high level	$C_L = 15 pF$,	See Figure 2		17	22	ns
tpzL	Output enable time to low level	$C_L = 15 pF$,	See Figure 3		20	25	ns
tPHZ	Output disable time from high level	$C_L = 5 pF$,	See Figure 2		21	30	ns
tPLZ	Output disable time from low level	$C_L = 5 pF$,	See Figure 3		30	40	ns

[†] All typical values are at V_{CC} = 5 V, T_A = 25°C. ‡ The algebraic convention, in which the less positive (more negative) limit is designated as minimum, is used in this data sheet for threshold voltage levels only.

PARAMETER MEASUREMENT INFORMATION

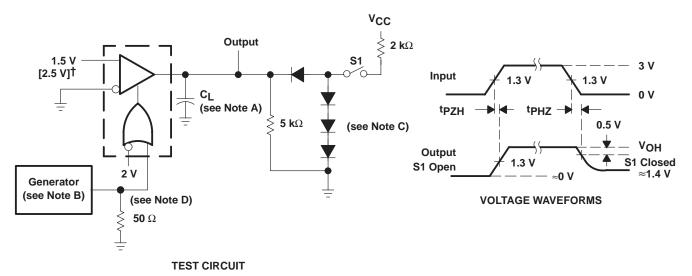


† Voltage for the SN55173 only.

NOTES: A. C_L includes probe and jig capacitance.

B. The input pulse is supplied by a generator having the following characteristics: PRR = 1 MHz, duty cycle = 50%, $t_f \le 6$ ns, $t_f \le 6$ ns

Figure 1. tpLH, tpHL Test Circuit and Voltage Waveforms



† Voltage for the SN55173 only.

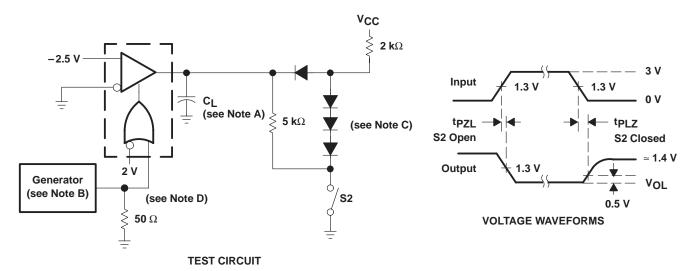
NOTES: A. C_L includes probe and jig capacitance.

- B. The input pulse is supplied by a generator having the following characteristics: PRR = 1 MHz, duty cycle = 50%, $t_f \le 6$ ns, $t_f \le 6$ ns
- C. All diodes are 1N916, or equivalent.
- D. To test the active-low enable \overline{G} , ground G and apply an inverted input waveform to \overline{G} .

Figure 2. t_{PHZ}, t_{PZH} Test Circuit and Voltage Waveforms



PARAMETER MEASUREMENT INFORMATION

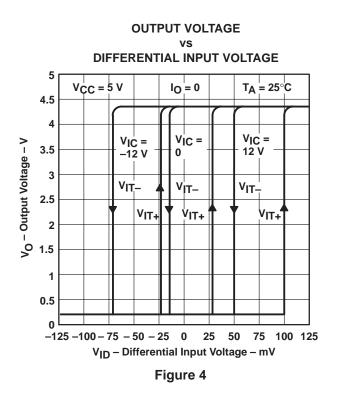


NOTES: A. C_L includes probe and jig capacitance.

- B. The input pulse is supplied by a generator having the following characteristics: PRR = 1 MHz, duty cycle = 50%, $t_f \le 6$ ns, $t_f \le 6$ ns
- C. All diodes are 1N916, or equivalent.
- D. To test the active-low enable \overline{G} , ground G and apply an inverted input waveform to \overline{G} .

Figure 3. tpzl, tpLZ Test Circuit and Voltage Waveforms

TYPICAL CHARACTERISTICS[†]



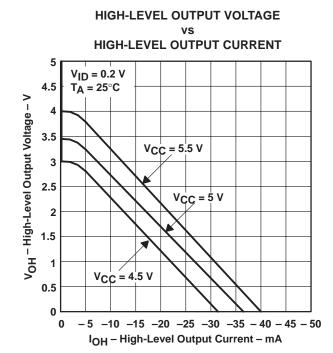
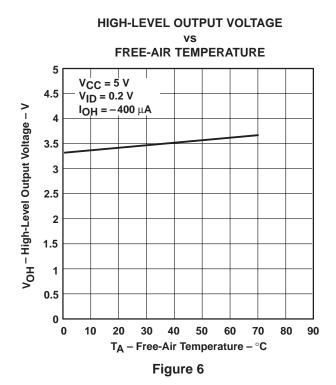


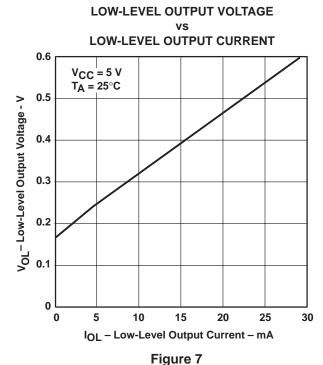
Figure 5

[†] Operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied.



TYPICAL CHARACTERISTICS[†]





LOW-LEVEL OUTPUT VOLTAGE
vs

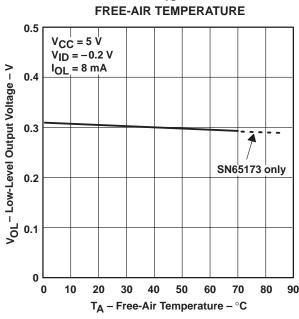
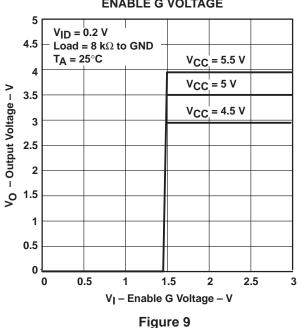


Figure 8

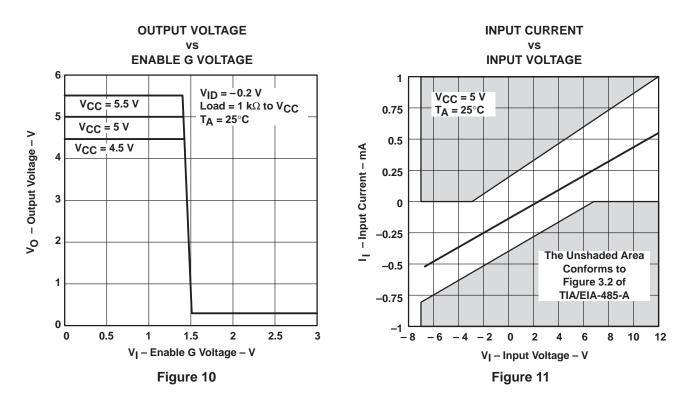
OUTPUT VOLTAGE vs ENABLE G VOLTAGE



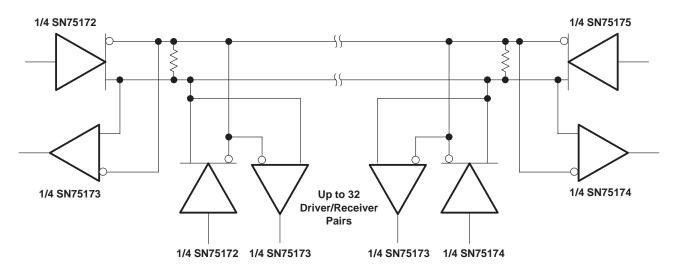
[†] Operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied.



TYPICAL CHARACTERISTICS



APPLICATION INFORMATION



NOTE A: The line should be terminated at both ends in its characteristic impedance. Stub lengths off the main line should be kept as short as possible.

Figure 12. Typical Application Circuit



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PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN55173J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN55173J	Samples
SN75173D	LIFEBUY	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	SN75173	
SN75173DR	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	SN75173	Samples
SN75173N	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN75173N	Samples
SN75173NSR	LIFEBUY	so	NS	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	SN75173	
SNJ55173J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ55173J	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

PACKAGE OPTION ADDENDUM

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OTHER QUALIFIED VERSIONS OF SN55173, SN75173:

Catalog: SN75173

Military: SN55173

NOTE: Qualified Version Definitions:

Catalog - TI's standard catalog product

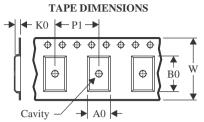
• Military - QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN75173DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN75173NSR	so	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

PACKAGE MATERIALS INFORMATION

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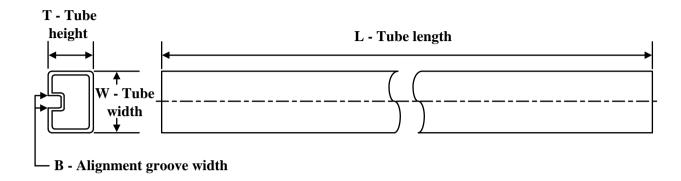
*All dimensions are nominal

Device	Package Type Package Drawing		Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN75173DR	SOIC	D	16	2500	340.5	336.1	32.0
SN75173NSR	SO	NS	16	2000	356.0	356.0	35.0

PACKAGE MATERIALS INFORMATION

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TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN75173D	D	SOIC	16	40	507	8	3940	4.32
SN75173N	N	PDIP	16	25	506	13.97	11230	4.32
SN75173N	N	PDIP	16	25	506	13.97	11230	4.32

14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.





SOP



- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing
- per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.



SOF



NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.

6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOP



NOTES: (continued)

- 7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 8. Board assembly site may have different recommendations for stencil design.



D (R-PDS0-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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